IXYS

Preliminary Technical Information

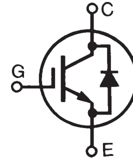
1200V XPT™ IGBT GenX3™ w/ Diode

IXYR50N120C3D1

V_{CES} = 1200V
I_{C90} = 32A
$V_{CE(sat)}$ ≤ 4.0V
$t_{fi(typ)}$ = 43ns

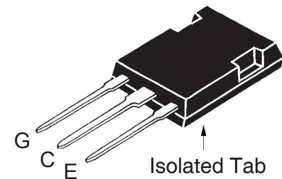
(Electrically Isolated Tab)

High-Speed IGBT
for 20-50 kHz Switching



Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	1200	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	1200	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (Chip Capability)	56	A
I_{C90}	T_C = 90°C	32	A
I_{F110}	T_C = 110°C	18	A
I_{CM}	T_C = 25°C, 1ms	210	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 150°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 100 @$V_{CE} \le V_{CES}$	A
P_C	T_C = 25°C	290	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
V_{ISOL}	50/60 Hz, 1 Minute	2500	V~
F_C	Mounting Force	20..120/4.5..27	N/lb.
Weight		5	g

ISOPLUS247™



G = Gate C = Collector
E = Emitter

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V~ Electrical Isolation
- Optimized for Low Switching Losses
- Square RBSOA
- Positive Thermal Coefficient of Vce(sat)
- Anti-Parallel Ultra Fast Diode
- High Current Handling Capability
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- High Frequency Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	1200			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			50	μA
	T_J = 125°C			500	μA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 50A, V_{GE} = 15V, Note 1			4.0	V
	T_J = 150°C		4.2		V

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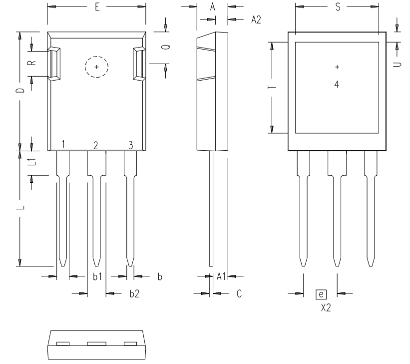
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 50A, V_{CE} = 10V, Note 1	20	32		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3100		pF
C_{oes}			230		pF
C_{res}			66		pF
$Q_{g(on)}$	I_C = 50A, V_{GE} = 15V, V_{CE} = 0.5 • V_{CES}		142		nC
Q_{ge}			23		nC
Q_{gc}			60		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		28		ns
t_{ri}	I_C = 50A, V_{GE} = 15V		62		ns
E_{on}	V_{CE} = 0.5 • V_{CES}, R_G = 5Ω		3.0		mJ
$t_{d(off)}$	Note 2		133		ns
t_{fi}			43		ns
E_{off}			1.0	1.7	mJ
$t_{d(on)}$	**Inductive load, T_J = 150°C**		28		ns
t_{ri}	I_C = 50A, V_{GE} = 15V		68		ns
E_{on}	V_{CE} = 0.5 • V_{CES}, R_G = 5Ω		6.0		mJ
$t_{d(off)}$	Note 2		160		ns
t_{fi}			60		ns
E_{off}			1.4		mJ
R_{thJC}				0.43	°C/W
R_{thCS}			0.15		°C/W

ISOPLUS247 (IXYR) Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.084	1.91	2.13
b2	.115	.123	2.92	3.12
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.800	19.81	20.32
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03

1 - Gate
2,4 - Collector
3 - Emiiter

Reverse Diode (FRED)

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)		Characteristic Value Min.	Typ.	Max.	
V_F	I_F = 30A, V_{GE} = 0V, Note 1				3.00	V
		T_J = 150°C		1.75		V
I_{RM}	I_F = 30A, V_{GE} = 0V, $-di_F/dt$ = 100A/μs,	T_J = 100°C			9	A
t_{rr}	V_R = 600V	T_J = 100°C		195		ns
R_{thJC}					1.10	°C/W

Notes:

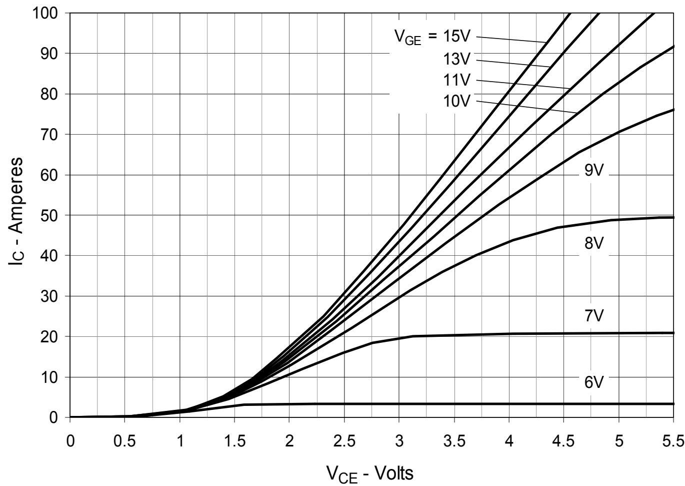
1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

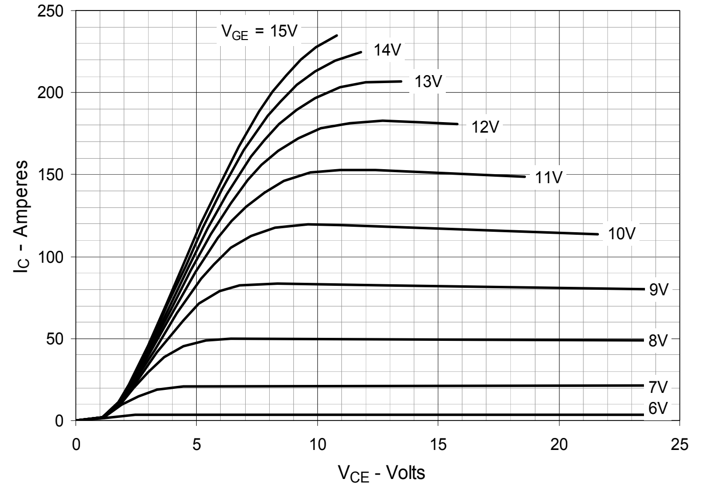
PRELIMANARY TECHNICAL INFORMATION

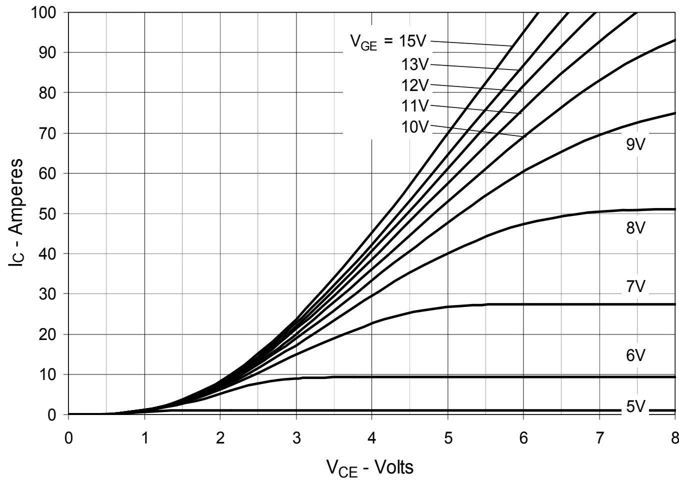
The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

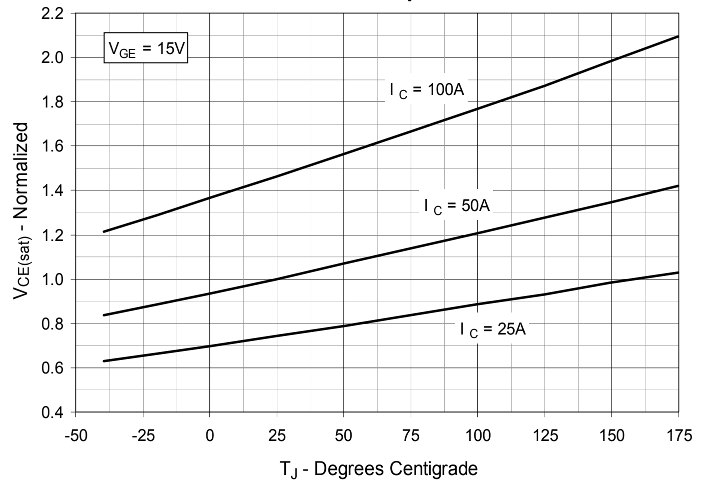
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

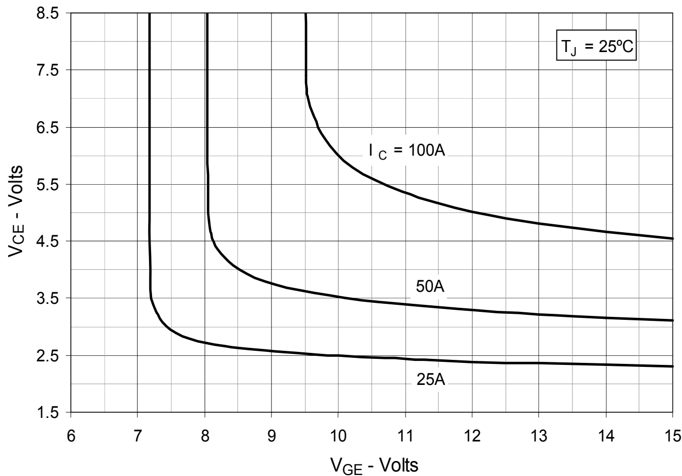
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

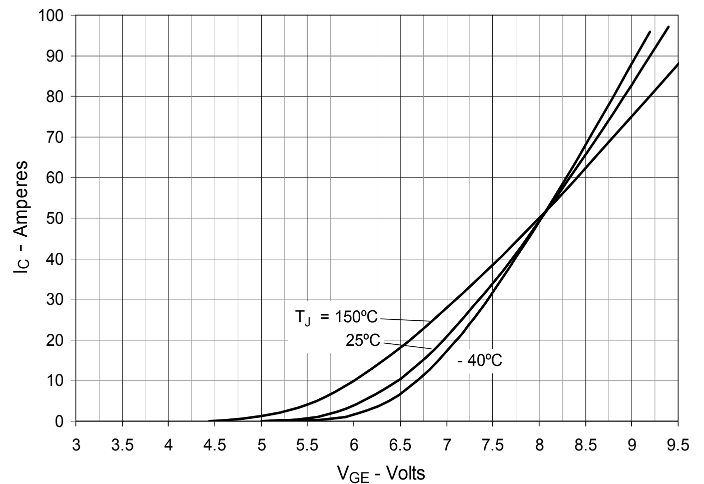












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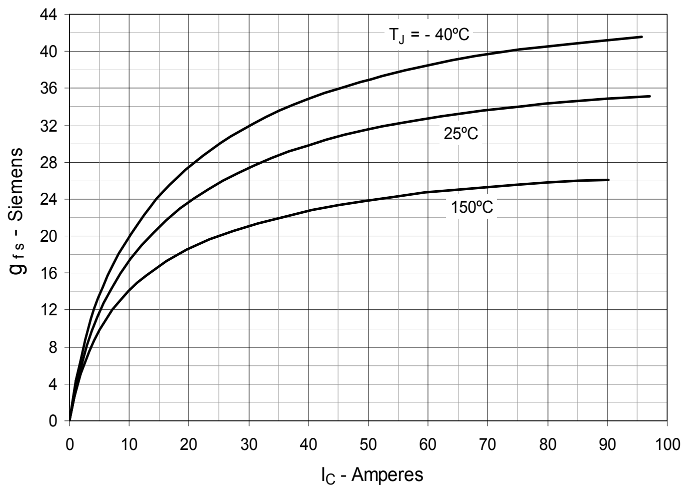


Fig. 7. Transconductance
T_J = - 40ºC
25ºC
150ºC
g_fs - Siemens
I_C - Amperes

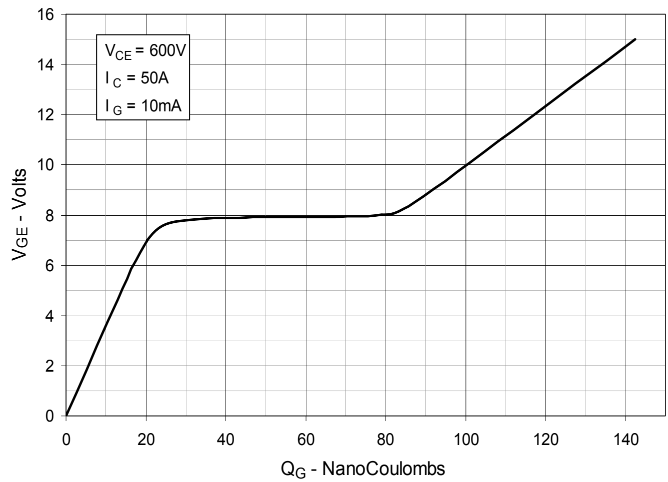


Fig. 8. Gate Charge
V_CE = 600V
I_C = 50A
I_G = 10mA
V_GE - Volts
Q_G - NanoCoulombs

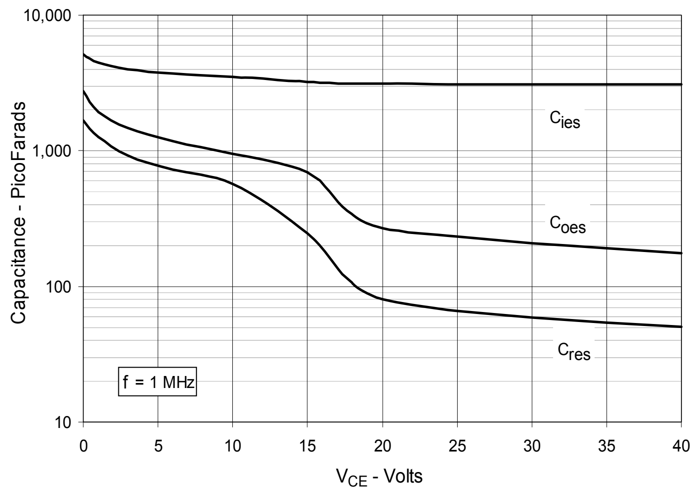


Fig. 9. Capacitance
C_ies
C_oes
C_res
f = 1 MHz
Capacitance - PicoFarads
V_CE - Volts

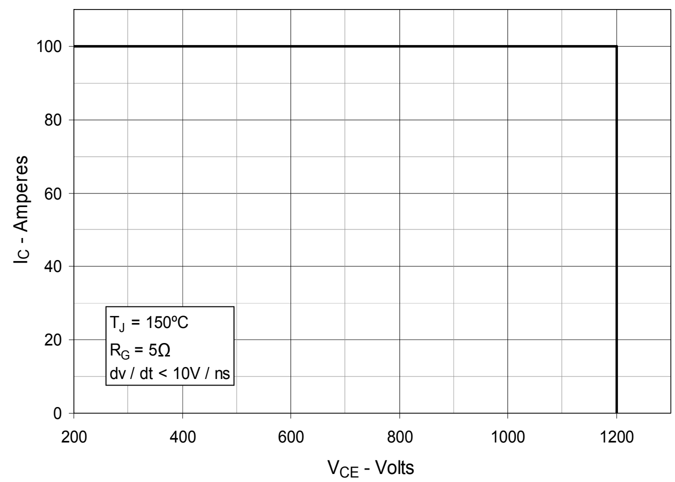


Fig. 10. Reverse-Bias Safe Operating Area
T_J = 150ºC
R_G = 5Ω
dv / dt < 10V / ns
I_C - Amperes
V_CE - Volts

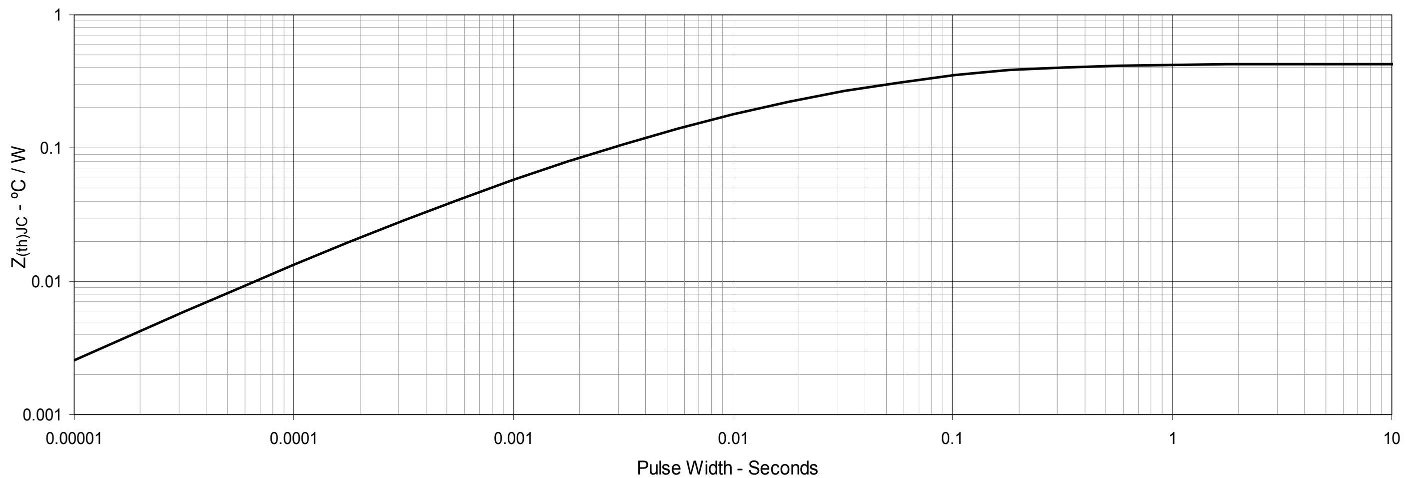


Fig. 11. Maximum Transient Thermal Impedance
Z_(th)JC - ºC / W
Pulse Width - Seconds

Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

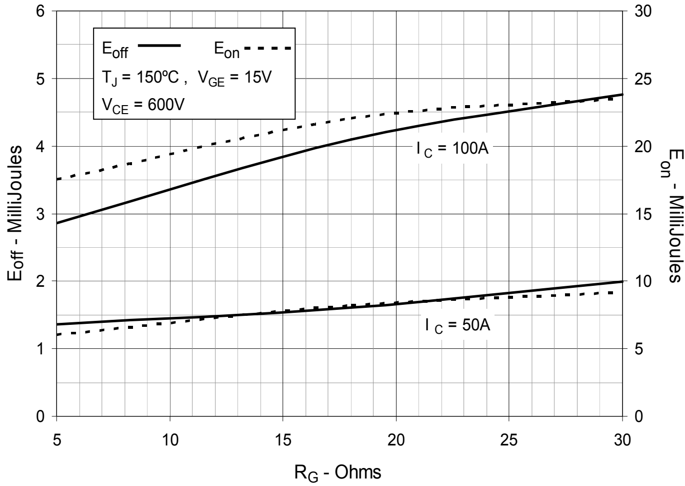


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

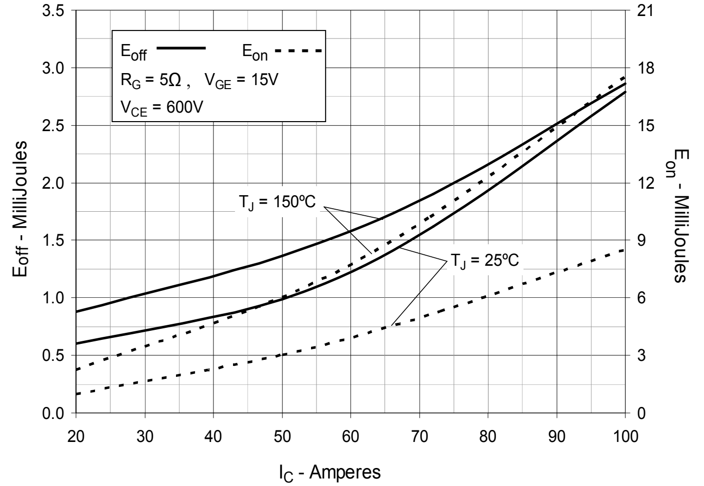


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

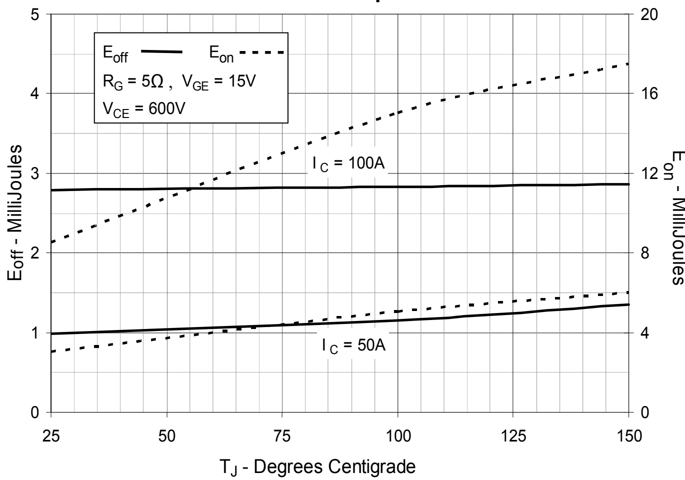


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

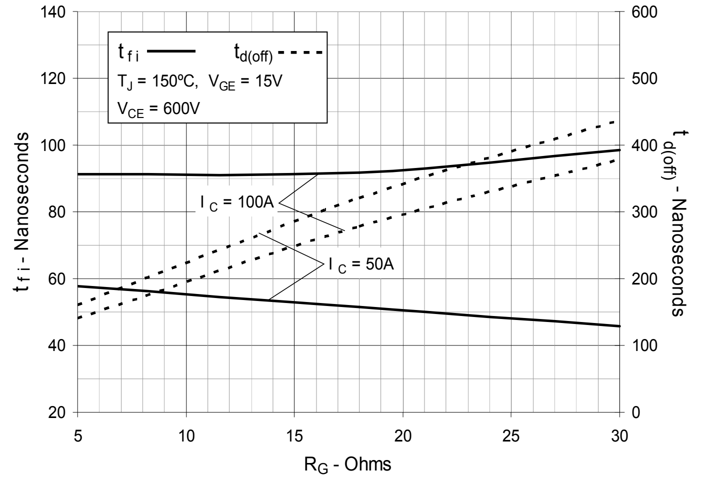


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

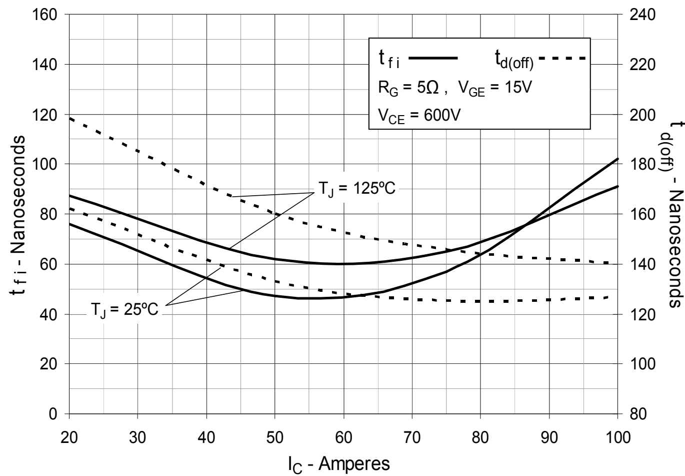
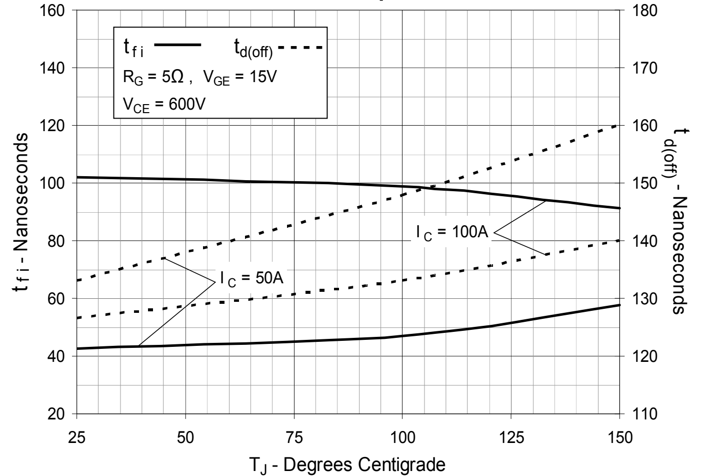


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature



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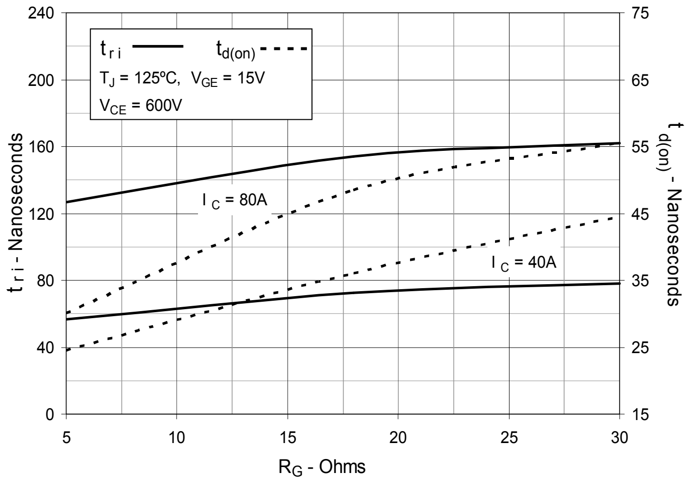
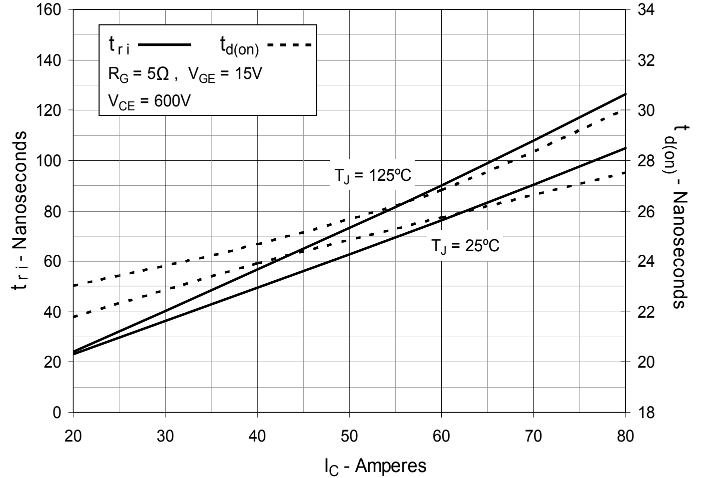
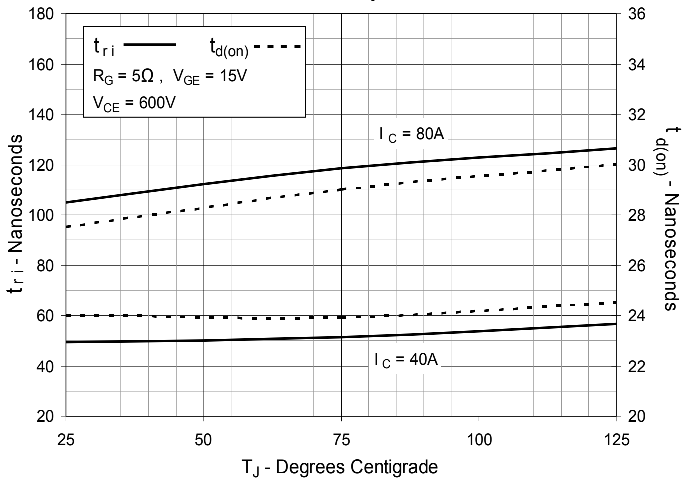
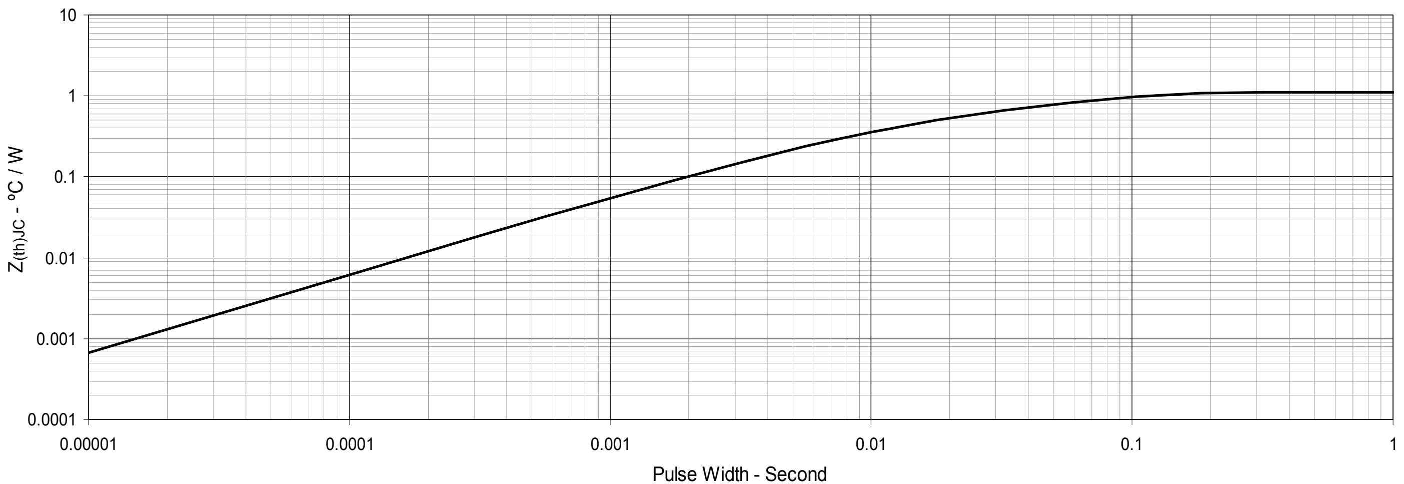








IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

Fig. 22. Forward Current I_F vs V_F

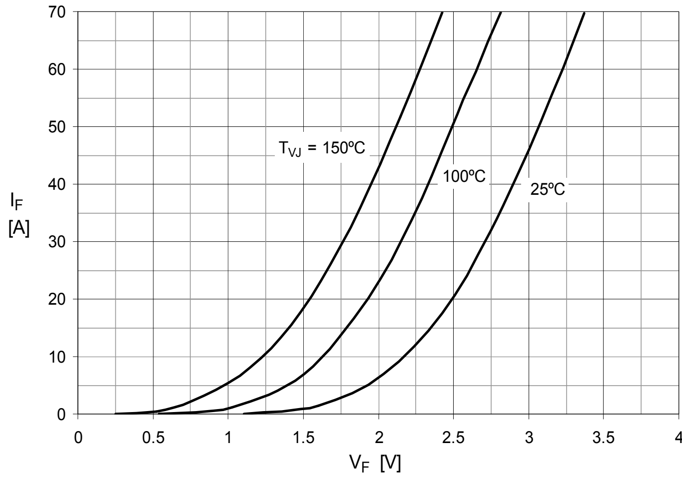


Fig. 23. Reverse Recovery Charge Q_{RM} vs. $-di_F/dt$

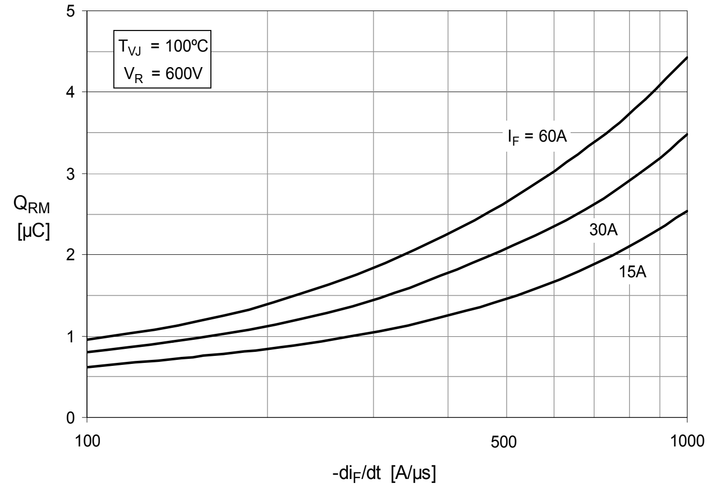


Fig. 24. Peak Reverse Current I_{RM} vs. $-di_F/dt$

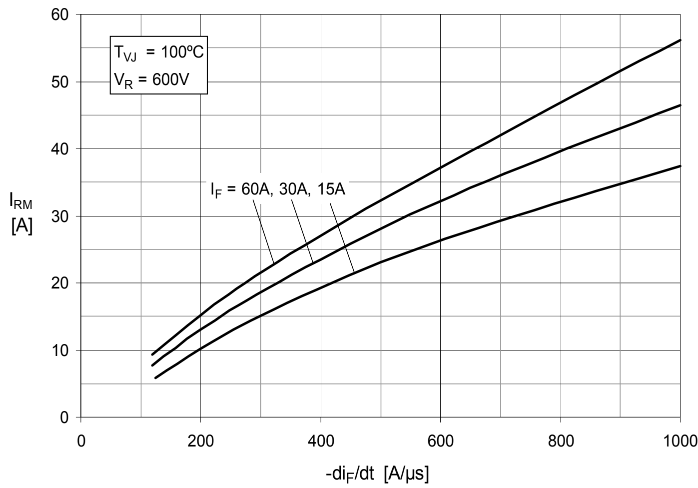


Fig. 25. Dynamic Parameters Q_{RM}, I_{RM} vs. T_{VJ}

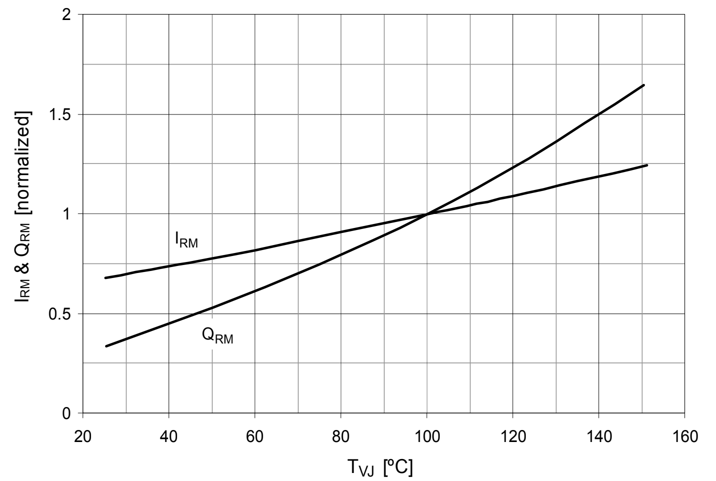


Fig. 26. Recovery Time t_{rr} vs. $-di_F/dt$

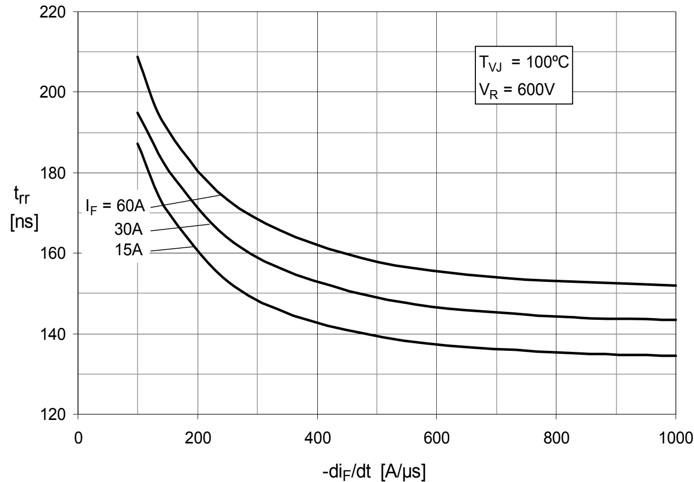
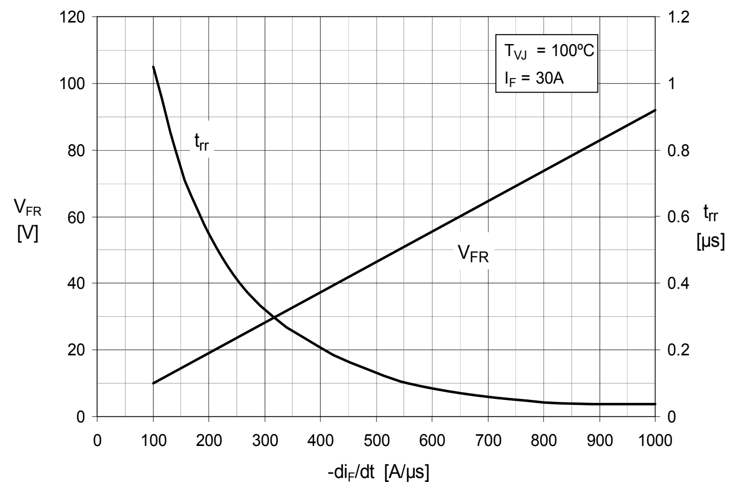


Fig. 27. Peak Forward Voltage V_{FR}, trr vs $-di_F/dt$



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